

# Infonote

## AO-IN-2024-029-I

### Introduction of New Die Attach (DA) Glue for SFH 2704

01.05.2024

Dear Customer,

Please take note of this **Infonote**.  
This customer notification is for information only and does not require customer approval.

Objective:	Introduction of New Die Attach (DA) Glue for SFH 2704	
Affected products:	Chip LED SFH 2704	
Reason for change:	New Die Attach (DA) glue will further improve the placement of the Photo Diode within the package with regards to die rotation and die position.	
Description of change:	<u>Current status</u>	<u>New status</u>
	Glue A	Glue B (with higher viscosity)
For details refer to file 2_cip_AO-IN-2024-029-I		
Time schedule:	Date code 2420	
Assessment:	The new die attach glue has been successfully qualified and has already been used to other ams-OSRAM products. No impact to form, fit and function of the device.	
Documentation:	2_cip_AO-IN-2024-029-I	

Material (Q-no.)	MDQ1	Product Family Name	Device Family
Q65112A7214	SFH 2704	Chip LED	SFH 2704
Q65113A2857	SFH 2704 C1004	Chip LED	SFH 2704A
Q65113A1284	SFH 2704 C1029	Chip LED	SFH 2704
Q65113A6652	SFH 2704 C1039	Chip LED	SFH 2704A
Q65113A7342	SFH 2704A	Chip LED	SFH 2704A